Disclaimer: Reference herein to any specific commercial company, product, process, or service by trade name, trademark, manufacturer, or otherwise, does not necessarily constitute or imply its endorsement, recommendation, or favoring by the United States Government or the Department of the Army (DoA). The opinions of the authors expressed herein do not necessarily state or reflect those of the United States Government or the DoA, and shall not be used for advertising or product endorsement purposes.



ADVANCES IN APPLICATION OF SILICON CARBIDE FOR HIGH POWER ELECTRONICS



Report Documentation Page				Form Approved OMB No. 0704-0188	
maintaining the data needed, a including suggestions for redu	and completing and reviewing the cing this burden, to Washington should be aware that notwithsta	e collection of information. Ser Headquarters Services, Directo	nd comments regarding this orate for Information Operate	burden estimate or a tions and Reports, 12	tions, searching existing data sources, gathering and ny other aspect of this collection of information, 115 Jefferson Davis Highway, Suite 1204, Arlington ling to comply with a collection of information if it
1. REPORT DATE	SPORT DATE 2. REPORT TYPE			3. DATES COVERED	
11 AUG 11	AUG 11 N/A			-	
4. TITLE AND SUBTIT		5a. CONTRACT NUMBER			
Advances in Application of silicon Carbide for High Power Electronics				5b. GRANT NUMBER	
				5c. PROGRAM ELEMENT NUMBER	
6. AUTHOR(S) James E. Gallagher				5d. PROJECT NUMBER	
				5e. TASK NUMBER	
				5f. WORK UNIT NUMBER	
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) SAIC				8. PERFORMING ORGANIZATION REPORT NUMBER 22156	
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES) US Army RDECOM-TARDEC 6501 E 11 Mile Rd Warren, MI 48397-5000, USA				10. SPONSOR/MONITOR'S ACRONYM(S) TACOM/TARDEC/RDECOM	
				11. SPONSOR/MONITOR'S REPORT NUMBER(S) 22156	
12. DISTRIBUTION/AVAILABILITY STATEMENT Approved for public release, distribution unlimited					
		•	_		ymposium 9-11 August 2011,
14. ABSTRACT					
15. SUBJECT TERMS					
16. SECURITY CLASSIFICATION OF:			17. LIMITATION	18.	19a. NAME OF RESPONSIBLE PERSON
a. REPORT unclassified	b. ABSTRACT unclassified	c. THIS PAGE unclassified	OF ABSTRACT SAR	NUMBER OF PAGES 17	





- Overview of SiC Advantages
- Prototype 150kW DC/DC Converter Description
- Initial Test Results / Requirements Compliance
- Test Plan / Schedule
- Conclusions
- Acknowledgements



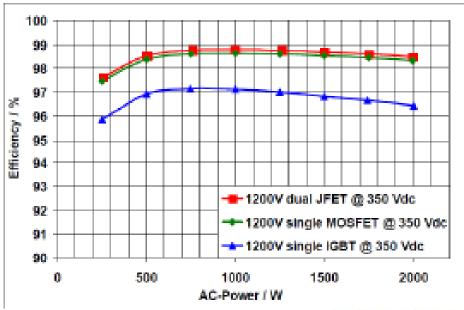


SiC Advantages



- Size, Weight & Performance Improved from Silicon:
 - Lower switching losses = substantially less waste heat
 - Higher operational switch junction temperatures = higher allowable coolant inlet temperature
 - Better thermal conductivity =
 better peak power capability
 - Higher switching frequencies = smaller capacitors & magnetics
 - Better radiation hardness = potentially simpler EMI/EMC design









System Advantages of SiC



- Cooling System Options
 - Increased top tank temperature allows:
 - Reduced radiator frontal area
 - Reduced cooling fan speed (proportional to fan power³)
 - Reductions to sizing (flow, pump, power) of the power electronics circuit
- Integration Flexibility
 - Integration locations previously inhospitable for power electronics placement
- However: Cost currently a significant disadvantage

Vehicle System Designers Can Balance These Advantages for Significant System Improvements



Prototype 150kW DC/DC Converter



Bi-Directional 150kW Unit

- 180kW Peak for 20s (discharge)
- 100°C Coolant Inlet
- 90°C Ambient
- Full-SiC MOSFET half-bridges
- Fiber optic communication interface
- 3.35 kW/liter, 1.8 kW/kg continuous ratings

High Voltage Conversion

- Galvanically isolated gate driver with gate voltage & over current monitoring, minimal recovery time, & failure memory
- 580-640Vdc propulsion bus
- 300-530Vdc "battery" bus
- 1200V, 100A switches
- 40-50kHz frequency used

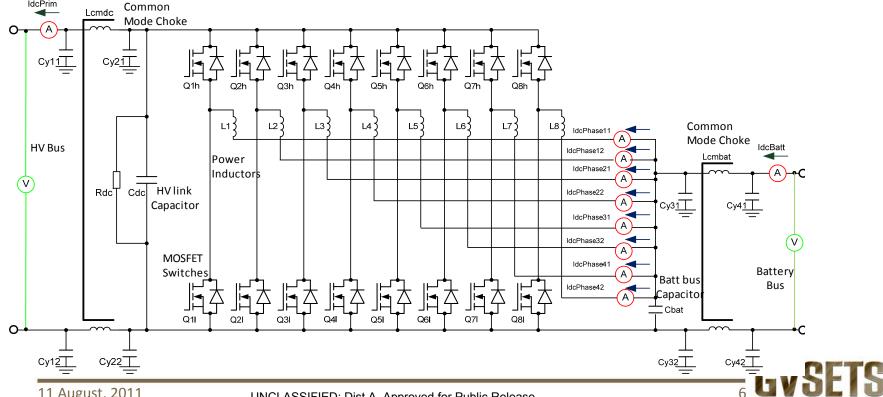




Prototype 150kW DC/DC Converter Architecture



- **Bi-Directional**
- Eight power phases with 45° phase shift (4x2)
- Individual power chokes
- Dual compartment layout (hot & cool)

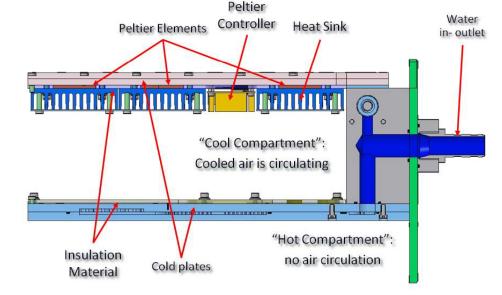




Key Design Challenges



- Two compartment design
 - Minimize development of new high-temp control electronics (scope, budget constraints)
 - Maintain a lower operating temperature for these items



- Peltier heat pump power supply
- Peltier heat pump controller (to improve part-power efficiency)

This development area retains significant room for future power density improvements as high temperature components become more readily available



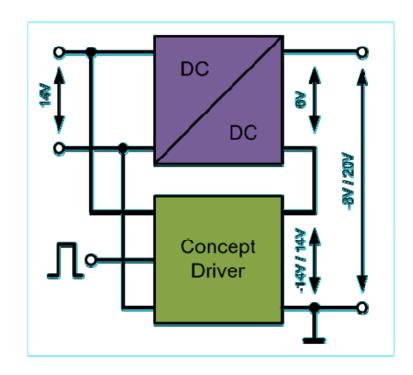


Key Design Challenges (Cont.)



Gate driver design

- Must reside with switches in hightemperature compartment
- Small board-mounted DC converters remain temperature sensitive cool compartment air circulated
- On/Off driver voltages of -8/+20 reduce conduction losses without need for adjustable output
- Separate sub-circuit gate drivers used to avoid parallel issues associated with MOSFETs



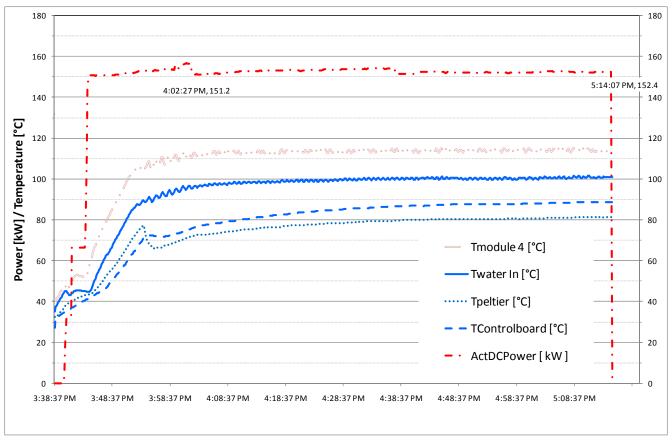




Initial Test Results (1 of 4)



Goal: 150kW Power, Up-Convert, 90°C ambient, 100°C coolant



Continuous power goal met

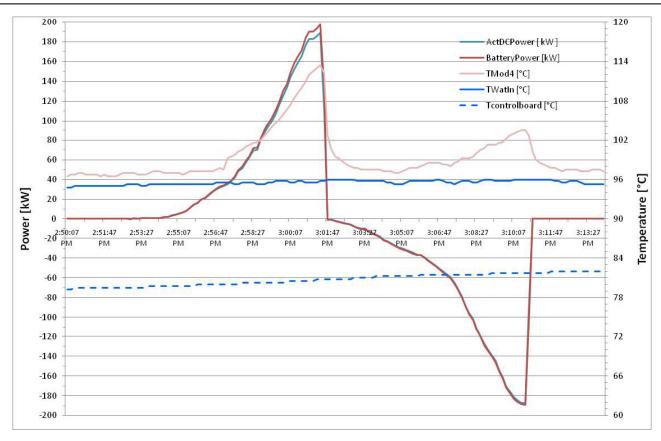




Initial Test Results (2 of 4)



Goal: 180kW Peak Power, 90°C ambient, 100°C coolant



Peak power goal met, charge & discharge

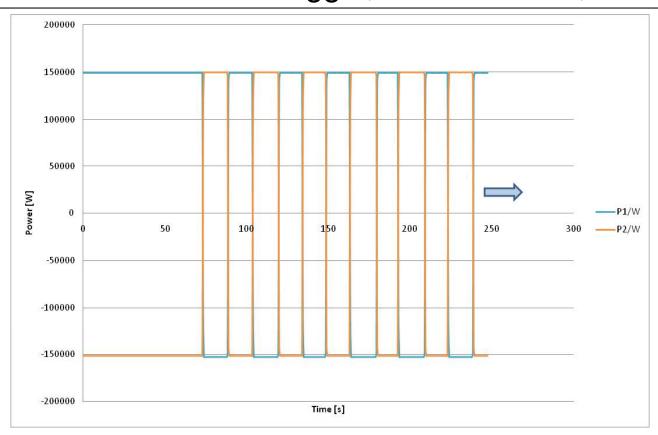




Initial Test Results (3 of 4)



Goal: Buck/Boost 150kW toggle, 90°C ambient, 100°C coolant



150kW Buck/Boost toggle goal met

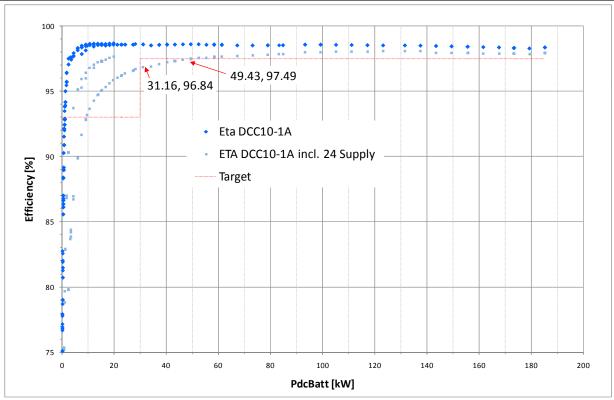




Initial Test Results (4 of 4)



Goal: Buck/Boost efficiency, 90°C ambient, 100°C coolant Shown with and without Peltier heat pump power supply



All efficiency targets met for P>2kW, without Peltier power supply





Requirements Compliance



- √ 150kW continuous operation
- √ 180kW discharge operation for >20s
- ✓ Voltage maintained within high & low side ranges
- √ 100°C coolant inlet full power operation
- √ 90°C ambient full power operation
- ✓ ≤12.5 liter/min & ≤172kPa ∆P
- ✓ ≥93% efficiency, 2-30kW*
- ✓ ≥97.5% efficiency, 30-180kW*
- ✓ <45 liters
- √ 3.3kW/liter (continuous 150kW rating)
- X 81kg (goal 75kg) due to added cooling complexity

Ambitious Goals – Significant Achievements

*For lower temperatures when the Peltier cooling system is not operating





Test Plan / Schedule



- Acceptance testing is underway at TARDEC labs
 - Verify steady-state operation up to 150kW and up to 100°C coolant inlet temperature
 - Verify peak operation at 180kW up to 100°C
 - Perform 150kW load cycling: +/-150kW in 15sec intervals for 30 minutes at 100°C coolant inlet temperature
 - Perform load-step testing to evaluate step response of DCC10
- Further testing is planned with TARDEC's Hybrid Electric Reconfigurable Moveable Integration Testbed (HERMIT) to evaluate the DCC10's performance in a real vehicle environment under typical operating conditions



Conclusions



- Power electronics designs are achievable with high temperature coolant and elevated ambient temperature
- The biggest drawback of this design has been the need for the Peltier cooling system, which can use up to 600W to cool the low-temperature electronics
- High temperature alternatives have been identified for many of the devices that currently reside in the cool compartment of the DCC10
- An improved design eliminating the need for the Peltier system would keep the efficiency of the next generation of converter above 98% down to about 10kW





Additional questions can be directed to:

Brian DeBlanc

L-3 Combat Propulsion Systems

Brian.deblanc@l-3com.com

231-855-0999



Acknowledgements



- Contributing authors:
 - Jens Friedrich L-3 Magnet Motor
 - Ed Leslie SAIC
 - Kay Peschke L-3 Magnet Motor
- DC Converter sponsors
 - TARDEC
 - SAIC